Filename: PMP8366\_REVA\_bom.xls

Date: 09/28/2012

## PMP8366\_REVA BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
	C1	0.1uF	Capacitor, Ceramic, 50V, X7R, 15%	0603	STD	STD
1	C10	0.022uF	Capacitor, Ceramic, 250V, X7R, 15%	0805	STD	STD
1	C100	0.47uF	Capacitor, Ceramic, 16V, X7R, 15%	0402	STD	STD
	C11, C18	0.1uF	Capacitor, Ceramic, 25V, X7R, 15%	0402	STD	STD
3	C12, C13, C14	22uF	Capacitor, Ceramic, 16V, X5R, 15%	1206	STD	STD
1	C15	330pF	Capacitor, Ceramic, 3kV, NP0, C0G, 10%	1808	Std	Std
1	C16	1uF	Capacitor, Ceramic, 6.3V, X5R, 15%	0402	STD	STD
1	C17	47pF	Capacitor, Ceramic, 50V, C0G, 5%	0402	STD	STD
2	C19, C101	1000pF	Capacitor, Ceramic, 50V, C0G, 5%	0402	STD	STD
4	C2, C3, C4, C5	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	STD	STD
1	C20	0.047uF	Capacitor, Ceramic, 25V, X7R, 15%	0402	STD	STD
1	C22	2200pF	Capacitor, Ceramic, 50V, C0G, 5%	0402	STD	STD
1	C23	4.7uF	Capacitor, Ceramic, 16V, X7R, 15%	1206	STD	STD
	C6, C7, C8	47uF	Capacitor, Ceramic, 16V, X7R, 15%	1210	STD	STD
1	C9	680uF	CAP ALUM 680UF 6.3V 20% RADIAL	0.315 inch		United Chemi-Con
8	D1, D3, D4, D5, D6, D7, D10, D11	MMDL914T1	Diode, Switching, 100-V, 200-mA, 200-mW,	SOD-323	MMDL914T1	On Semi
	D2	ES1D	DIODE ULTRAFAST 200V 1A DO-214AC	SMA	ES1D-13-F	Diodes Inc.
	D8, D9	5.6V	Diode, Zener, 5.6V	SOD-323	BZT52B5V6S	STD
5	J1, J2, J5, J6, J7	8600-0-05-01-00-00-03-0	Header, Single pin	0.072 x 1 inch	8600-0-05-01-00-00-03-0	
2	J3, J4		Header, Single pin	0.125 x 1 inch	8952-0-05-01-00-00-03-0	
1	L1	2.2uH	Inductor, Shielded Power, ±20%		XAL1010-222ME	Coilcraft
1	L2	1mH	Inductor, SMT, 0.1A, ±20%	0.189 x 0.189 inch	LPS5015-105ML	Coilcraft
	Q1. Q6	CSD17312Q5	MOSFET, NChan, 30V, 30A, 1.8 milliOhm	QFN5X6mm	CSD17312Q5	TI
	Q100	MMBT2907ALT1	Transistor, PNP, -60V, -600mA, 225-W	QLINOXOIIIII	MMBT2907ALT1	11
1	Q2	FDMS86200	MOSFET N-CH 150V POWER56	QFN	FDMS86200	Fairchild
1	Q3	SI1411DH	MOSFET P-CH 150V 420MA SC70-6	TSOP-6	SI1411DH	Vishay
2	Q4, Q5	DXT2222A-13	TRANSISTOR BIPO NPN 40V SOT89-3	SOT-89	DXT2222A-13	Diodes Inc.
1	Q7	2N7002W	MOSFET, Nch, 60V, 115mA	SOT323 [SC70]	2N7002W	Diodes inc.
	R1	4.3	Resistor, Chip. 1/16W. 1%	0603	STD	STD
1	R100	301	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R12	66.5k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
4	R13, R15, R21, R27	100k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R14	52.3k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R16	6.81k	Resistor, Chip, 1/16W, 1% Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R17	0.01K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R19	3.74k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
4	R2. R8. R10. R24	3.74k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
4	R20	1.65k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R22	499		0402	Std	Std
1	R23	100	Resistor, Chip, 1/16W, 1%	0402	STD	STD
			Resistor, Chip, 1/16W, 1%			
1	R29 R3	49.9k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	-	7.15k	Resistor, Chip, 1/2W, 5%	2010	STD	STD
	R4, R6	2k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
6	R5, R11, R25, R26, R28, R31	10k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R7, R18	1k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R9	15k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	T1	CST2-100L	Transformer, Current Sense, 100:1	0.315 x 0.320 inch	CST2-100L	Coilcraft
1	T2	140 uH	Transformer, High Fq Plannar, 100W, 48V to 5V, 20A	20.1x23.4 mm	PA0634	Pulse
2	U1, U4	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay
1	U2	UCC2897ARTJ	IC, Advanced Current-Mode Active Clamp PWM Controller	QFP-20	UCC2897ARTJ	TI
2	U3, U5	TL431AIDBZR	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZR	TI

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